

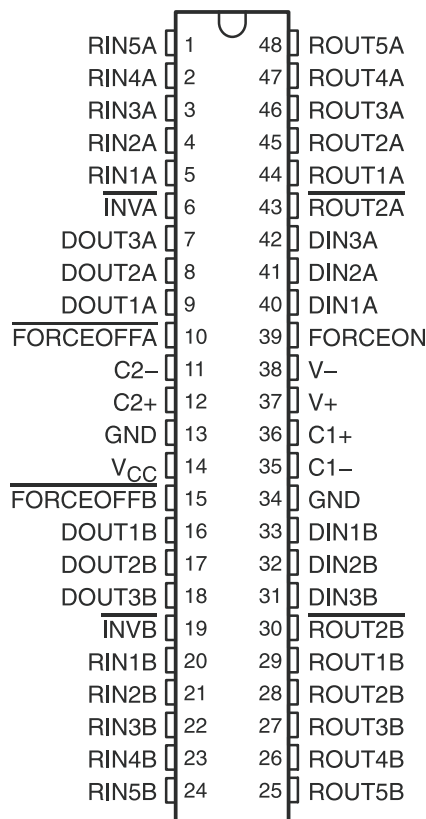
## FEATURES

- Single-Chip and Single-Supply Interface for Two IBM PC/AT Serial Ports
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V  $V_{CC}$  Supply
- Always-Active Noninverting Receiver Output ( $\overline{ROUT2}$ ) Per Port
- Operates Up To 250 kbit/s
- Low Standby Current . . . 1  $\mu$ A Typical
- External Capacitors . . .  $4 \times 0.22 \mu$ F
- Accepts 5-V Logic Input With 3.3-V Supply
- Allows for Flexible Power Down of Either Serial Port
- Serial-Mouse Driveability
- RS-232 Bus-Pin ESD Protection Exceeds  $\pm 15$  kV Using Human-Body Model (HBM)

## APPLICATIONS

- Battery-Powered Systems
- Notebooks
- Laptops
- Palmtop PCs
- Hand-Held Equipment

DGG OR DL PACKAGE  
(TOP VIEW)



## DESCRIPTION/ORDERING INFORMATION

The TRSF23243 consists of two ports, each containing three line drivers and five line receivers, and a dual charge-pump circuit with  $\pm 15$ -kV ESD protection pin to pin (serial-port connection pins, including GND). This device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches that needed for two typical serial ports used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, this device includes an always-active noninverting output ( $\overline{ROUT2}$ ) per port, which allows applications using the ring indicator to transmit data while the device is powered down. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ $\mu$ s driver output slew-rate.

### ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SSOP – DL	Tube of 25	TRSF23243CDL	TRSF23243C
		Reel of 1000	TRSF23243CDLR	
	TSSOP – DGG	Reel of 2000	TRSF23243CDGGR	TRSF23243C
–40°C to 85°C	SSOP – DL	Tube of 25	TRSF23243IDL	TRSF23243I
		Reel of 1000	TRSF23243IDLR	
	TSSOP – DGG	Reel of 2000	TRSF23243IDGGR	TRSF23243I

(1) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

Flexible control options for power management are available when either or both serial ports are inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs of its respective port are disabled. If FORCEOFF is set low, both drivers and receivers (except ROUT2) are shut off, and the supply current is reduced to 1  $\mu$ A. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when FORCEON and FORCEOFF are high and should be done when driving a serial mouse. With auto-powerdown enabled, the RS-232 port is activated automatically when a valid signal is applied to any respective receiver input. The INV output is used to notify the user if an RS-232 signal is present at any receiver input. INV is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30  $\mu$ s. INV is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30  $\mu$ s. Refer to Figure 5 for receiver input levels.

### FUNCTION TABLES

Each Driver<sup>(1)</sup>  
(Each Port)

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown disabled
H	H	H	X	L	
L	L	H	Yes	H	Normal operation with auto-powerdown enabled
H	L	H	Yes	L	
L	L	H	No	Z	Powered off by auto-powerdown feature
H	L	H	No	Z	

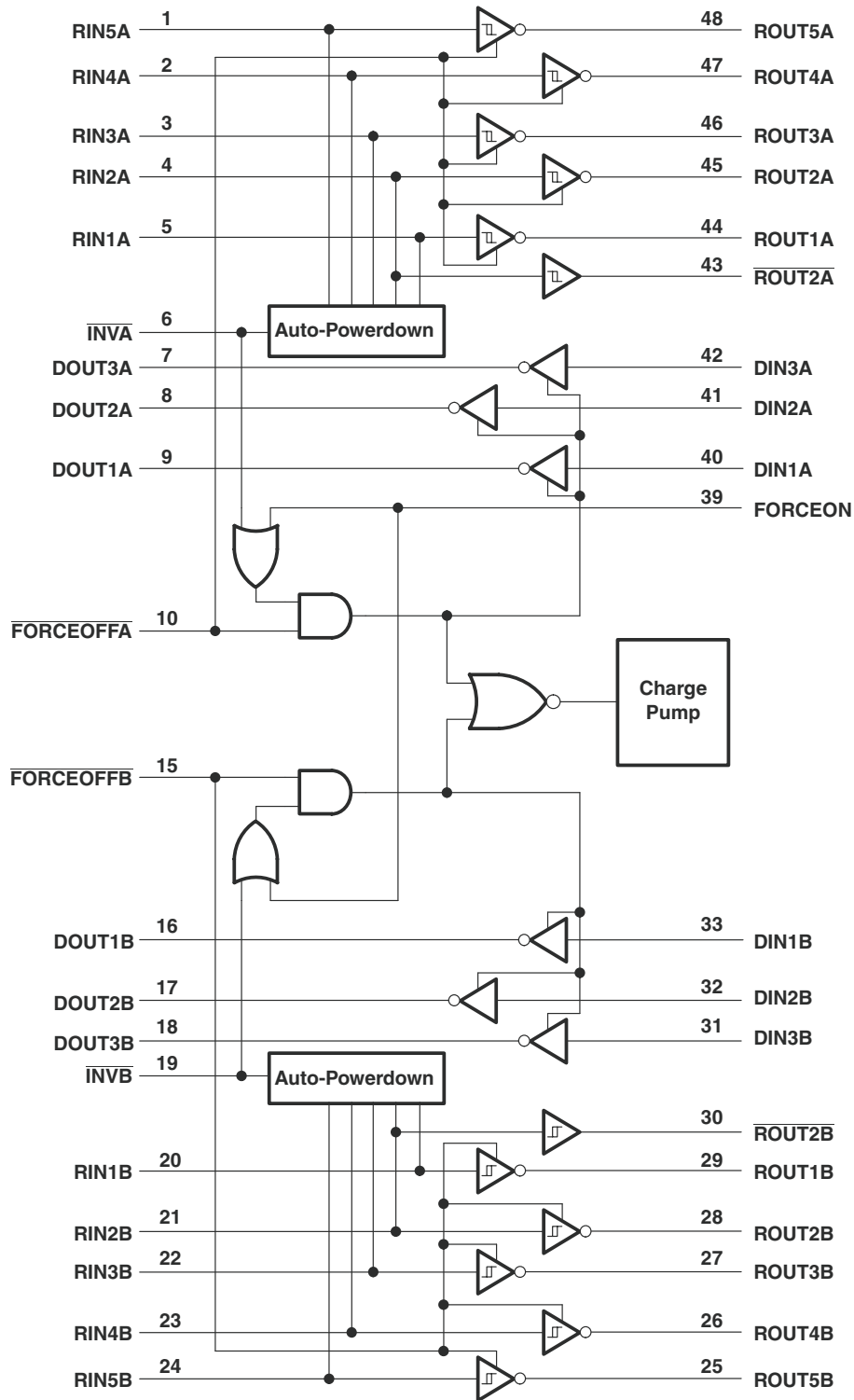
(1) H = high level, L = low level, X = irrelevant, Z = high impedance

Each Receiver<sup>(1)</sup>  
(Each Port)

INPUTS				OUTPUTS		RECEIVER STATUS
RIN2	RIN1, RIN3–RIN5	FORCEOFF	VALID RIN RS-232 LEVEL	ROUT2	ROUT	
L	X	L	X	L	Z	Powered off while ROUT2 is active
H	X	L	X	H	Z	
L	L	H	Yes	L	H	Normal operation with auto-powerdown disabled/enabled
L	H	H	Yes	L	L	
H	L	H	Yes	H	H	
H	H	H	Yes	H	L	
Open	Open	H	No	L	H	

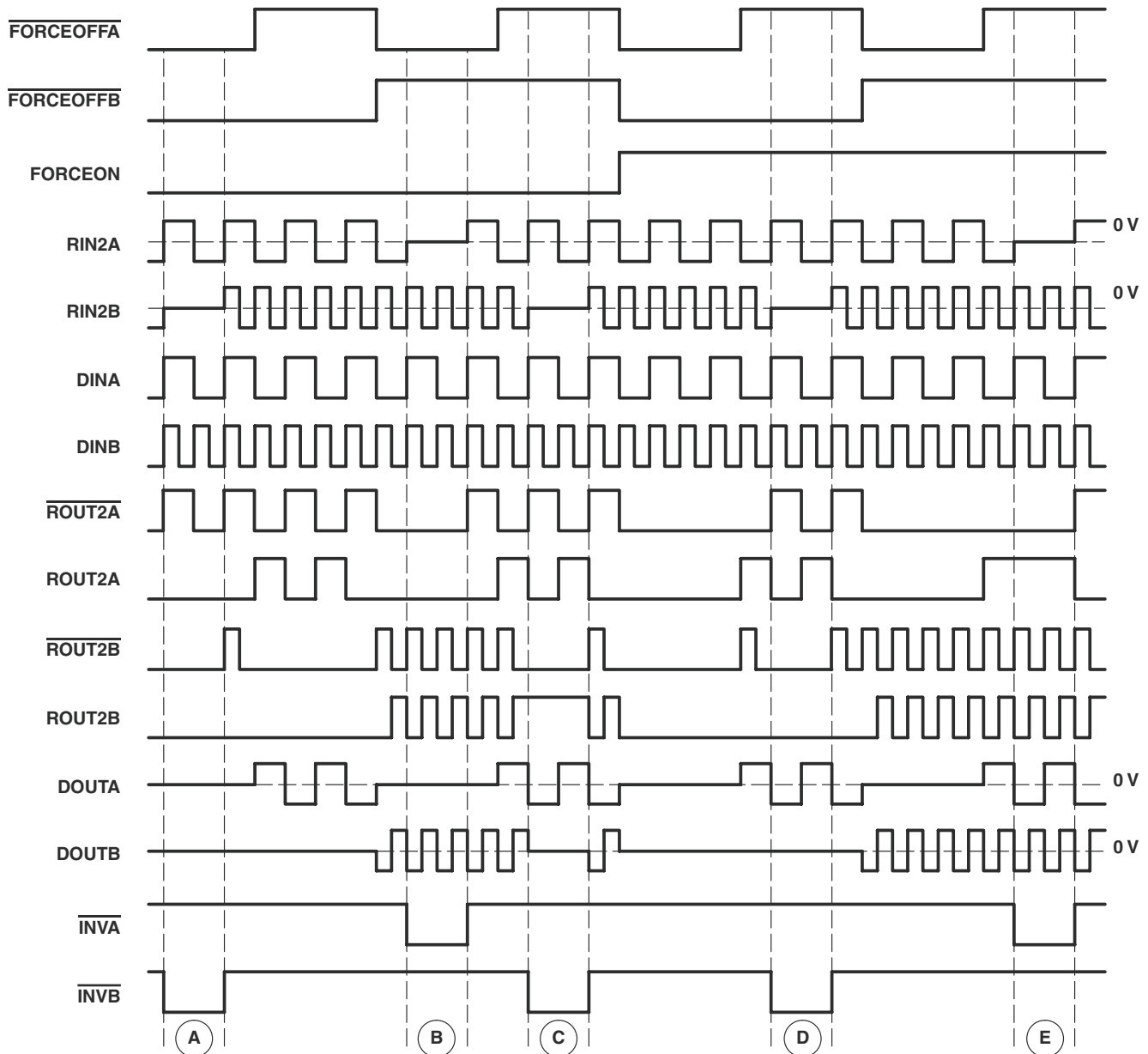
(1) H = high level, L = low level, X = irrelevant,  
Z = high impedance (off),  
Open = input disconnected or connected driver off

**LOGIC DIAGRAM (POSITIVE LOGIC)**



## Timing

Figure 1 shows how the two independent serial ports can be enabled or disabled. As shown by the logic states, depending on the  $\overline{\text{FORCEOFF}}$ ,  $\text{FORCEON}$ , and receiver input levels, either port can be powered down. Intermediate receiver input levels indicate a 0-V input. Also, it is assumed a pulldown resistor to ground is used for the receiver outputs. The  $\overline{\text{INV}}$  pin goes low when its respective receiver input does not supply a valid RS-232 level. For simplicity, voltage levels, timing differences, and input/output edge rates are not shown.



- Ports A and B manually powered off.
- Port A manually powered off, port B in normal operation with auto-powerdown enabled.
- Port B powered off by auto-powerdown, port A in normal operation with auto-powerdown enabled.
- Port A in normal operation with auto-powerdown disabled, port B manually powered off.
- Ports A and B in normal operation with auto-powerdown disabled

**Figure 1. Timing Diagram**

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range <sup>(2)</sup>	–0.3	6	V
V+	Positive-output supply voltage range <sup>(2)</sup>	–0.3	7	V
V–	Negative-output supply voltage range <sup>(2)</sup>	0.3	–7	V
V+ – V–	Supply voltage difference <sup>(2)</sup>		13	V
V <sub>I</sub>	Input voltage range	Driver (FORCEOFF, FORCEON)		V
		Receiver		
V <sub>O</sub>	Output voltage range	Driver		V
		Receiver (INV)		
θ <sub>JA</sub>	Package thermal impedance <sup>(3)(4)</sup>	DGG package		°C/W
		DL package		
T <sub>J</sub>	Operating virtual junction temperature		150	°C
T <sub>stg</sub>	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) Maximum power dissipation is a function of T<sub>J</sub>(max), θ<sub>JA</sub>, and T<sub>A</sub>. The maximum allowable power dissipation at any allowable ambient temperature is P<sub>D</sub> = (T<sub>J</sub>(max) – T<sub>A</sub>)/θ<sub>JA</sub>. Operating at the absolute maximum T<sub>J</sub> of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

## Recommended Operating Conditions<sup>(1)</sup>

See [Figure 7](#)

		MIN	NOM	MAX	UNIT
Supply voltage	V <sub>CC</sub> = 3.3 V	3	3.3	3.6	V
		V <sub>CC</sub> = 5 V	4.5	5	
V <sub>IH</sub>	Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V <sub>CC</sub> = 3.3 V		V
			V <sub>CC</sub> = 5 V		
V <sub>IL</sub>	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON		0.8	V
V <sub>I</sub>	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0	V
	Receiver input voltage	–25	25		
T <sub>A</sub>	Operating free-air temperature	TRSF23243C		0	°C
		TRSF23243I		–40	

- (1) Test conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

## Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 7](#))

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
I <sub>I</sub>	Input leakage current	FORCEOFF, FORCEON		±0.01	±1	μA
I <sub>CC</sub>	Supply current (T <sub>A</sub> = 25°C)	Auto-powerdown disabled	No load, FORCEOFF and FORCEON at V <sub>CC</sub>	0.6	2	mA
		Powered off	No load, FORCEOFF at GND	1	20	
		Auto-powerdown enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded	1	20	μA

- (1) Test conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.
- (2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

## DRIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 7](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub>	High-level output voltage All DOUT at R <sub>L</sub> = 3 kΩ to GND	5	5.4		V
V <sub>OL</sub>	Low-level output voltage All DOUT at R <sub>L</sub> = 3 kΩ to GND	-5	-5.4		V
V <sub>O</sub>	Output voltage (mouse driveability) DIN1 = DIN2 = GND, DIN3 = V <sub>CC</sub> , 3-kΩ to GND at DOUT3, DOUT1 = DOUT2 = -2.5 mA	±5			V
I <sub>IH</sub>	High-level input current V <sub>I</sub> = V <sub>CC</sub>		±0.01	±1	μA
I <sub>IL</sub>	Low-level input current V <sub>I</sub> at GND		±0.01	±1	μA
I <sub>OS</sub>	Short-circuit output current <sup>(3)</sup> V <sub>CC</sub> = 3.6 V      V <sub>O</sub> = 0 V V <sub>CC</sub> = 5.5 V      V <sub>O</sub> = 0 V		±35	±60	mA
r <sub>O</sub>	Output resistance V <sub>CC</sub> , V+, and V- = 0 V,      V <sub>O</sub> = ±2 V	300	10M		Ω
I <sub>OZ</sub>	Output leakage current FORCEOFF = GND, V <sub>O</sub> = ±12 V,      V <sub>CC</sub> = 3 V to 3.6 V V <sub>O</sub> = ±10 V,      V <sub>CC</sub> = 4.5 V to 5.5 V			±25 ±25	μA

(1) Test conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 7](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT	
Maximum data rate	R <sub>L</sub> = 3 kΩ, One DOUT switching C <sub>L</sub> = 1000 pF, See <a href="#">Figure 2</a>	250			kbit/s	
t <sub>sk(p)</sub>	Pulse skew <sup>(3)</sup> C <sub>L</sub> = 150 pF to 2500 pF,      R <sub>L</sub> = 3 kΩ to 7 kΩ,      See <a href="#">Figure 2</a>		100		ns	
SR(tr)	Slew rate, transition region (see <a href="#">Figure 2</a> ) V <sub>CC</sub> = 3.3 V, R <sub>L</sub> = 3 kΩ to 7 kΩ			6 4	30 30	V/μs

(1) Test conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Pulse skew is defined as |t<sub>PLH</sub> - t<sub>PHL</sub>| of each channel of the same device.

## RECEIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 7](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub> High-level output voltage	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> - 0.6	V <sub>CC</sub> - 0.1		V
V <sub>OL</sub> Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V
V <sub>IT+</sub> Positive-going input threshold voltage	V <sub>CC</sub> = 3.3 V		1.6	2.4	V
	V <sub>CC</sub> = 5 V		1.9	2.4	
V <sub>IT-</sub> Negative-going input threshold voltage	V <sub>CC</sub> = 3.3 V	0.6	1.1		V
	V <sub>CC</sub> = 5 V	0.8	1.4		
V <sub>hys</sub> Input hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.5		V
I <sub>OZ</sub> Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	µA
r <sub>I</sub> Input resistance	V <sub>I</sub> = ±3 V to ±25 V	3	5	7	kΩ

(1) Test conditions are C1–C4 = 0.22 µF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V<sub>CC</sub> = 5 V ± 0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 3](#))

PARAMETER	TEST CONDITIONS	TYP <sup>(2)</sup>	UNIT
t <sub>PLH</sub> Propagation delay time, low- to high-level output	C <sub>L</sub> = 150 pF, See <a href="#">Figure 4</a>	150	ns
t <sub>PHL</sub> Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF, See <a href="#">Figure 4</a>	150	ns
t <sub>en</sub> Output enable time	C <sub>L</sub> = 150 pF, See <a href="#">Figure 5</a> R <sub>L</sub> = 3 kΩ,	200	ns
t <sub>dis</sub> Output disable time	C <sub>L</sub> = 150 pF, See <a href="#">Figure 5</a> R <sub>L</sub> = 3 kΩ,	200	ns
t <sub>sk(p)</sub> Pulse skew <sup>(3)</sup>	See <a href="#">Figure 4</a>	50	ns

(1) Test conditions are C1–C4 = 0.22 µF at V<sub>CC</sub> = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2–C4 = 0.33 µF at V<sub>CC</sub> = 5 V ± 0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Pulse skew is defined as |t<sub>PLH</sub> - t<sub>PHL</sub>| of each channel of the same device.

## AUTO-POWERDOWN SECTION

### Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for $\overline{INV}$ high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$		2.7	V
$V_{T(valid)}$	Receiver input threshold for $\overline{INV}$ high-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-2.7		V
$V_{T(invalid)}$	Receiver input threshold for $\overline{INV}$ low-level output voltage	FORCEON = GND,	$\overline{FORCEOFF} = V_{CC}$	-0.3	0.3	V
$V_{OH}$	$\overline{INV}$ high-level output voltage	$I_{OH} = -1\text{ mA}$ , $\overline{FORCEOFF} = V_{CC}$	FORCEON = GND,	$V_{CC} - 0.6$		V
$V_{OL}$	$\overline{INV}$ low-level output voltage	$I_{OL} = 1.6\text{ mA}$ , $\overline{FORCEOFF} = V_{CC}$	FORCEON = GND,		0.4	V

### Switching Characteristics

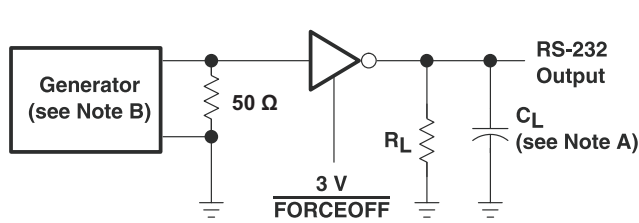
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER		TYP <sup>(1)</sup>	UNIT
$t_{valid}$	Propagation delay time, low- to high-level output	1	$\mu\text{s}$
$t_{invalid}$	Propagation delay time, high- to low-level output	30	$\mu\text{s}$
$t_{en}$	Supply enable time	100	$\mu\text{s}$

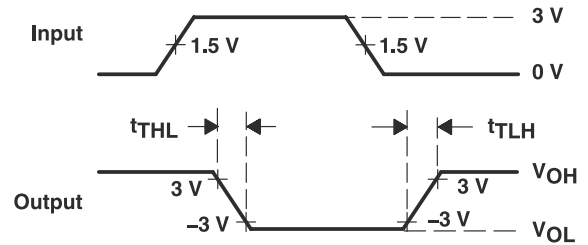
(1) All typical values are at  $V_{CC} = 3.3\text{ V}$  or  $V_{CC} = 5\text{ V}$ , and  $T_A = 25^\circ\text{C}$ .



PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

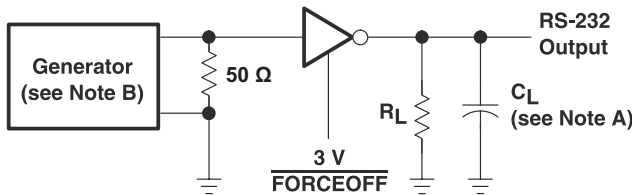


VOLTAGE WAVEFORMS

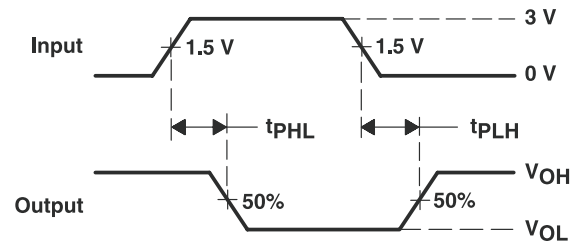
$$SR(tr) = \frac{6 V}{t_{THL} \text{ or } t_{TLH}}$$

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbits/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 2. Driver Slew Rate



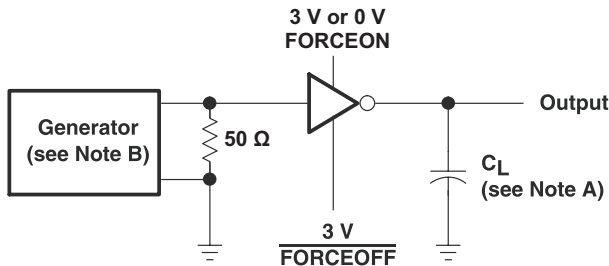
TEST CIRCUIT



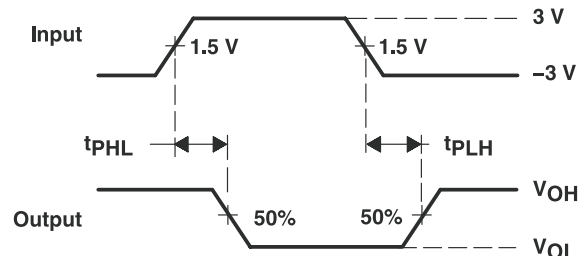
VOLTAGE WAVEFORMS

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbits/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 3. Driver Pulse Skew



TEST CIRCUIT

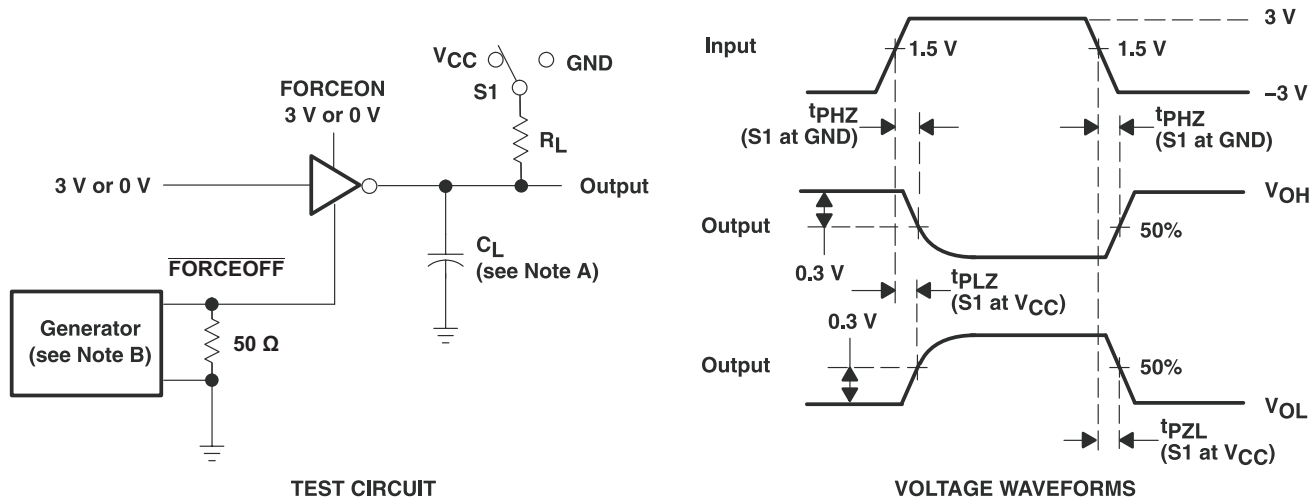


VOLTAGE WAVEFORMS

- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbits/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 4. Receiver Propagation Delay Times

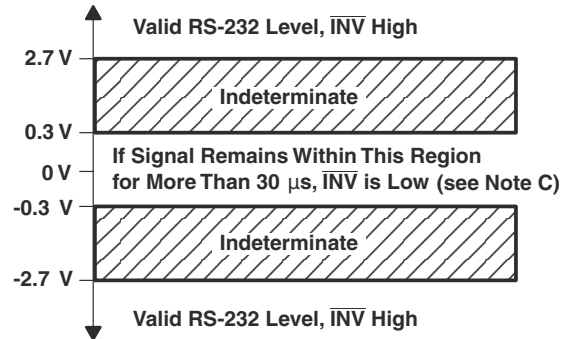
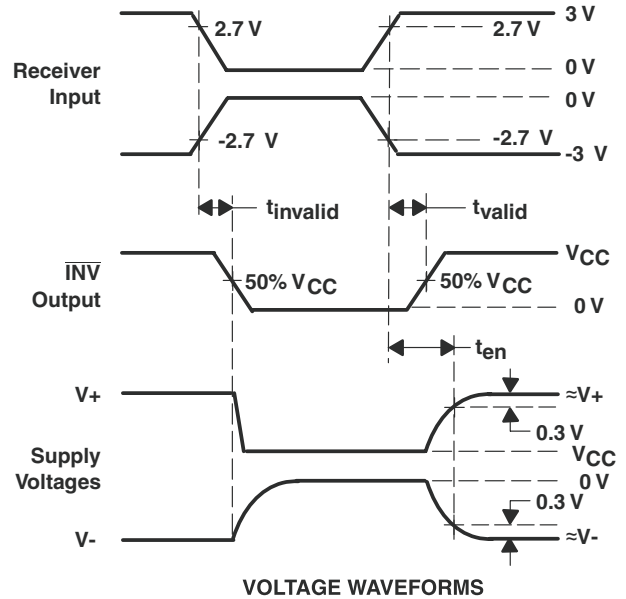
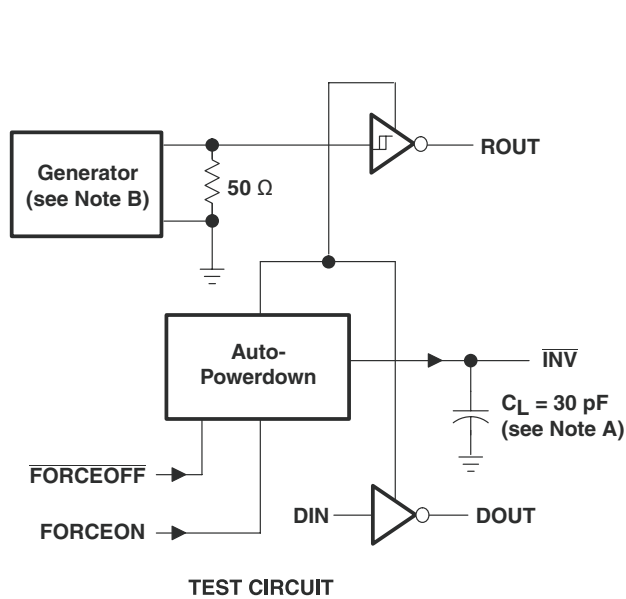
PARAMETER MEASUREMENT INFORMATION (continued)



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbits/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.
- C.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- D.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .

Figure 5. Receiver Enable and Disable Times

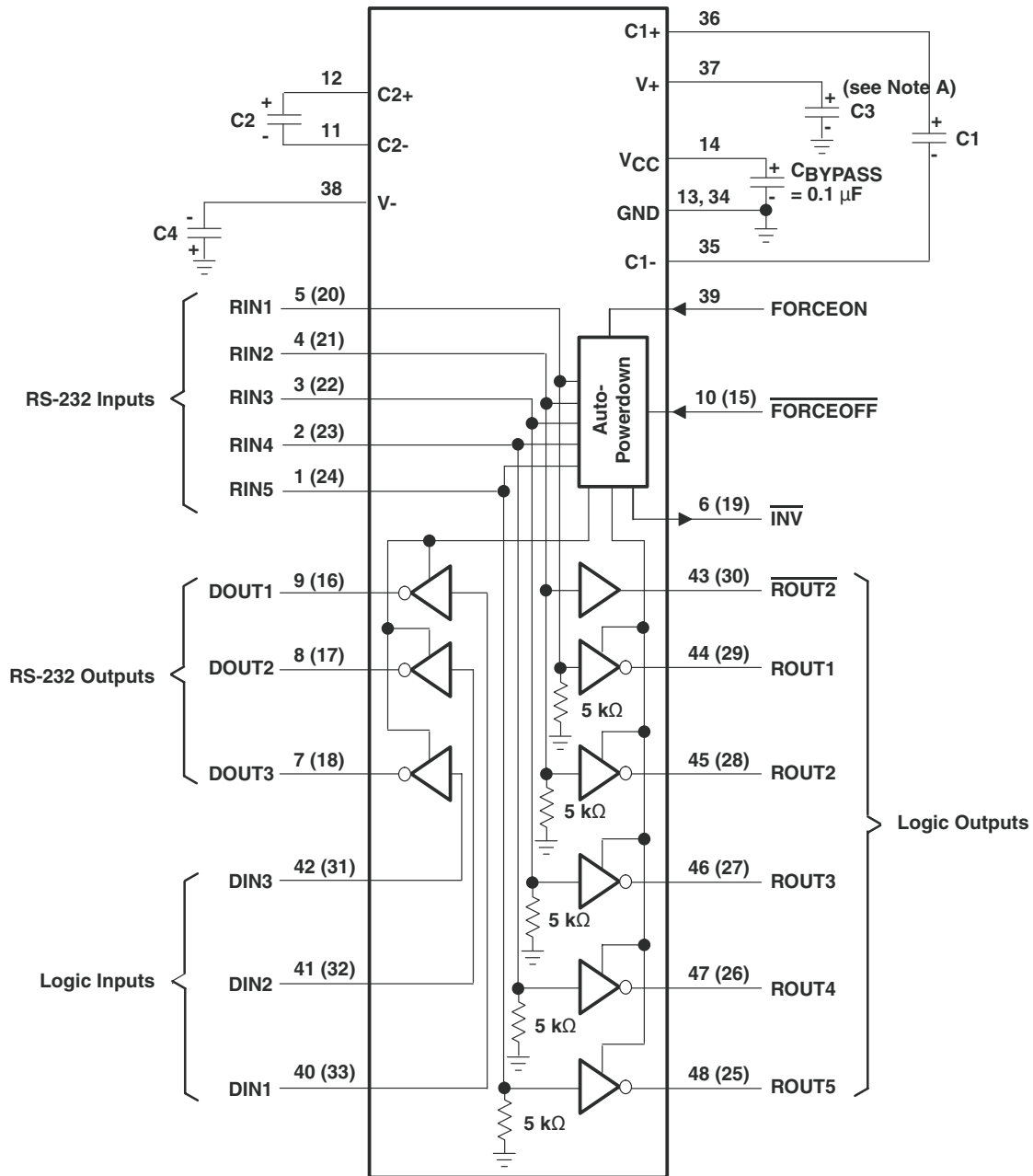
PARAMETER MEASUREMENT INFORMATION (continued)



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbits/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns.

Figure 6.  $\overline{INV}$  Propagation Delay Times and Supply Enabling Times

APPLICATION INFORMATION



V<sub>CC</sub> vs CAPACITOR VALUES

V <sub>CC</sub>	C1	C2, C3, and C4
3.3 V ± 0.3 V	0.22 μF	0.22 μF
5 V ± 0.5 V	0.047 μF	0.33 μF
3 V to 5.5 V	0.22 μF	1 μF

- A. C3 can be connected to V<sub>CC</sub> or GND.
- B. Resistor values shown are nominal.
- C. Numbers in parentheses are for B section.

Figure 7. Typical Operating Circuit and Capacitor Values

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TRSF23243CDGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRSF23243C	<a href="#">Samples</a>
TRSF23243CDLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRSF23243C	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

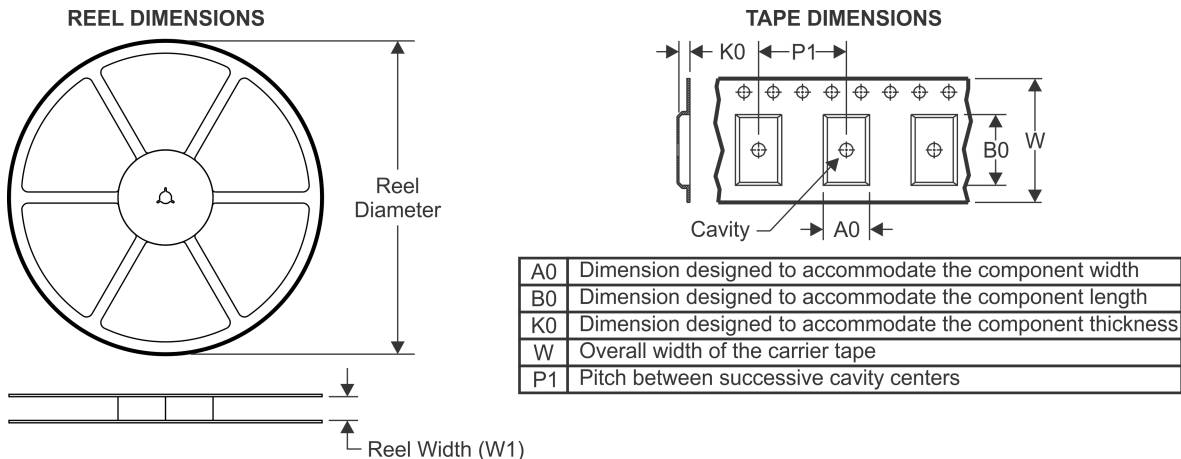
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRSF23243CDGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
TRSF23243CDLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

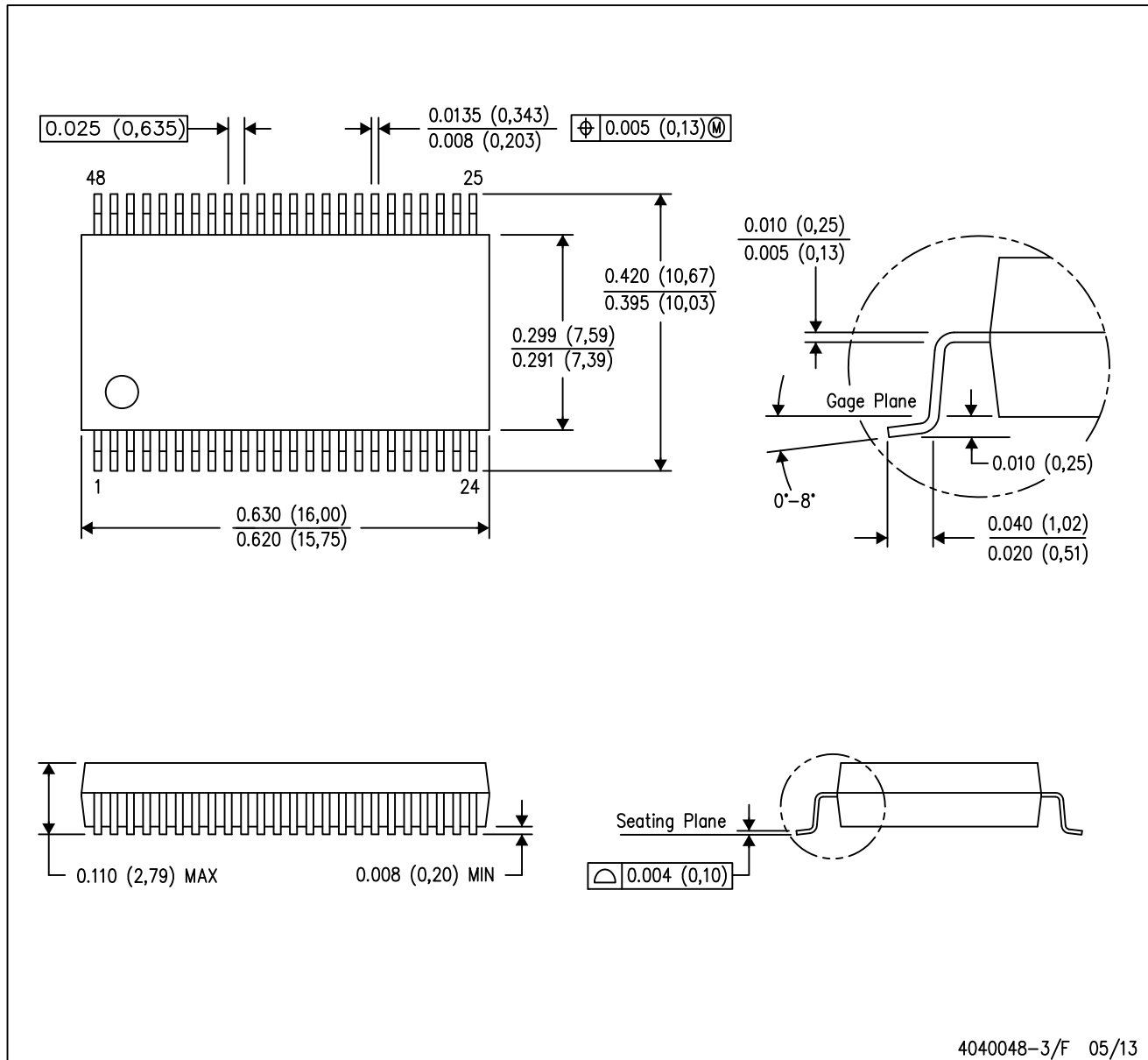
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRSF23243CDGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
TRSF23243CDLR	SSOP	DL	48	1000	367.0	367.0	55.0



# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

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DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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